



## Material Content Data Sheet



<b>Sales Product Name</b>		TLE5501 E0002		<b>Issued</b>		31. July 2018		
<b>MA#</b>		MA001827584						
<b>Package</b>		PG-DSO-8-16		<b>Weight*</b>		82.86 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.430	0.52	0.52	5191	5191
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		433	
	non noble metal	iron	7439-89-6	0.717	0.87		8655	
wire	non noble metal	copper	7440-50-8	29.121	35.14	36.06	351449	360645
	noble metal	gold	7440-57-5	0.177	0.21	0.21	2139	2139
	encapsulation	organic material	carbon black	1333-86-4	0.101	0.12		1213
encapsulation	plastics	epoxy resin	-	4.624	5.58		55807	
	inorganic material	silicondioxide	60676-86-0	45.538	54.98	60.68	549582	606602
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9822	9822
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7848	7848
glue	plastics	epoxy resin	-	0.161	0.19		1938	
	noble metal	silver	7440-22-4	0.482	0.58	0.77	5815	7753
*deviation	< 10%					Sum in total:	100.00	1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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